

### General Description

The HSH18N20A is the highest performance SGT N-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The HSH18N20A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

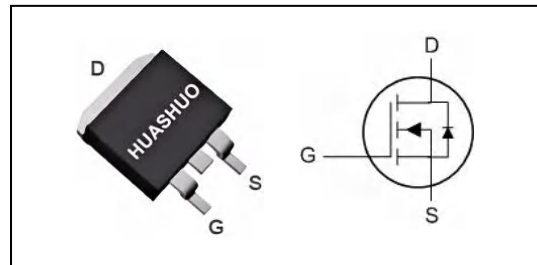
### Features

- Super Low Gate Charge
- Green Device Available
- Excellent  $C_{dv/dt}$  effect decline
- Advanced high cell density SGT MOS Technology

### Product Summary

|                  |     |            |
|------------------|-----|------------|
| $V_{DS}$         | 200 | V          |
| $R_{DS(ON),typ}$ | 95  | m $\Omega$ |
| $I_D$            | 18  | A          |

### TO-263 Pin Configuration



### Absolute Maximum Ratings

| Symbol                      | Parameter                                  | Rating     | Units            |
|-----------------------------|--------------------------------------------|------------|------------------|
| $V_{DS}$                    | Drain-Source Voltage                       | 200        | V                |
| $V_{GS}$                    | Gate-Source Voltage                        | $\pm 20$   | V                |
| $I_D@T_C=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 18         | A                |
| $I_D@T_C=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 11         | A                |
| $I_D@T_A=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 2.7        | A                |
| $I_D@T_A=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 2.2        | A                |
| $I_{DM}$                    | Pulsed Drain Current <sup>2</sup>          | 36         | A                |
| EAS                         | Single Pulse Avalanche Energy <sup>3</sup> | 40         | mJ               |
| $I_{AS}$                    | Avalanche Current                          | 28         | A                |
| $P_D@T_C=25^\circ\text{C}$  | Total Power Dissipation <sup>3</sup>       | 85         | W                |
| $P_D@T_A=25^\circ\text{C}$  | Total Power Dissipation <sup>3</sup>       | 2          | W                |
| $T_{STG}$                   | Storage Temperature Range                  | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                       | Operating Junction Temperature Range       | -55 to 150 | $^\circ\text{C}$ |

### Thermal Data

| Symbol          | Parameter                                        | Typ. | Max. | Unit               |
|-----------------|--------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 60   | $^\circ\text{C/W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 1.1  | $^\circ\text{C/W}$ |



### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol              | Parameter                                      | Conditions                                                                               | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------------------------|------------------------------------------------------------------------------------------|------|------|------|------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA                                               | 200  | ---  | ---  | V    |
| R <sub>DS(ON)</sub> | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =10A                                                | ---  | 95   | 120  | mΩ   |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA                                 | 2    | 2.9  | 3.5  | V    |
| I <sub>DSS</sub>    | Drain-Source Leakage Current                   | V <sub>DS</sub> =160V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                         | ---  | ---  | 1    | uA   |
|                     |                                                | V <sub>DS</sub> =160V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                         | ---  | ---  | 5    |      |
| I <sub>GSS</sub>    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                               | ---  | ---  | ±100 | nA   |
| R <sub>g</sub>      | Gate Resistance                                | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz                                         | ---  | 0.9  | ---  | Ω    |
| Q <sub>g</sub>      | Total Gate Charge (10V)                        | V <sub>DS</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A                         | ---  | 14   | ---  | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge                             |                                                                                          | ---  | 3.9  | ---  |      |
| Q <sub>gd</sub>     | Gate-Drain Charge                              |                                                                                          | ---  | 3.5  | ---  |      |
| T <sub>d(on)</sub>  | Turn-On Delay Time                             | V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω<br>I <sub>D</sub> =10A | ---  | 8.3  | ---  | ns   |
| T <sub>r</sub>      | Rise Time                                      |                                                                                          | ---  | 18.2 | ---  |      |
| T <sub>d(off)</sub> | Turn-Off Delay Time                            |                                                                                          | ---  | 15   | ---  |      |
| T <sub>f</sub>      | Fall Time                                      |                                                                                          | ---  | 3.8  | ---  |      |
| C <sub>iss</sub>    | Input Capacitance                              | V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f=1MHz                                       | ---  | 887  | ---  | pF   |
| C <sub>oss</sub>    | Output Capacitance                             |                                                                                          | ---  | 49   | ---  |      |
| C <sub>rss</sub>    | Reverse Transfer Capacitance                   |                                                                                          | ---  | 5.3  | ---  |      |

### Diode Characteristics

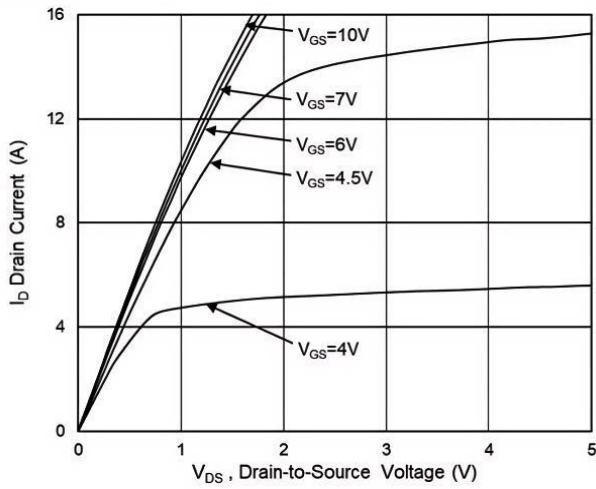
| Symbol          | Parameter                                | Conditions                                                    | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------------------|---------------------------------------------------------------|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current <sup>1,5</sup> | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current             | ---  | ---  | 18   | A    |
| I <sub>SM</sub> | Pulsed Source Current <sup>2,5</sup>     |                                                               | ---  | ---  | 36   | A    |
| V <sub>SD</sub> | Diode Forward Voltage <sup>2</sup>       | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C | ---  | ---  | 1.2  | V    |
| t <sub>rr</sub> | Reverse Recovery Time                    | I <sub>F</sub> =10A, dI/dt=100A/μs, T <sub>J</sub> =25°C      | ---  | 87   | ---  | nS   |
| Q <sub>rr</sub> | Reverse Recovery Charge                  | T <sub>J</sub> =25°C                                          | ---  | 303  | ---  | nC   |

Note :

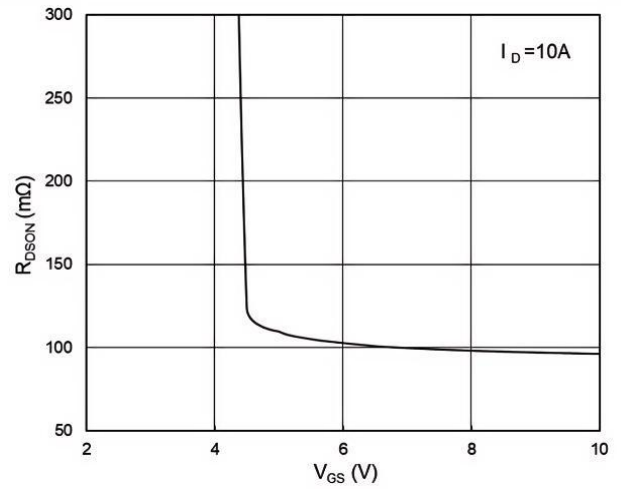
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=28A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



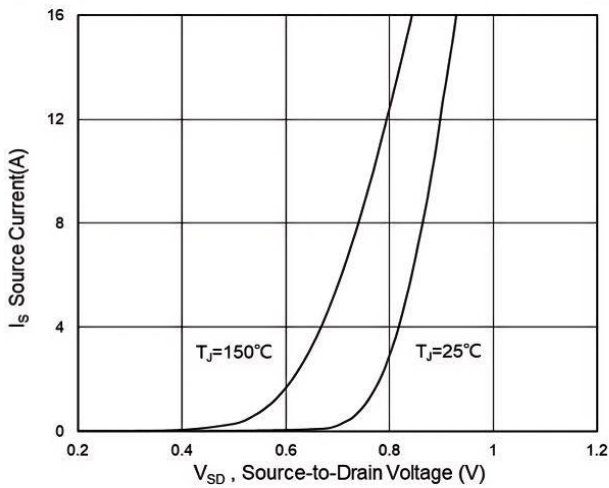
### Typical Characteristics



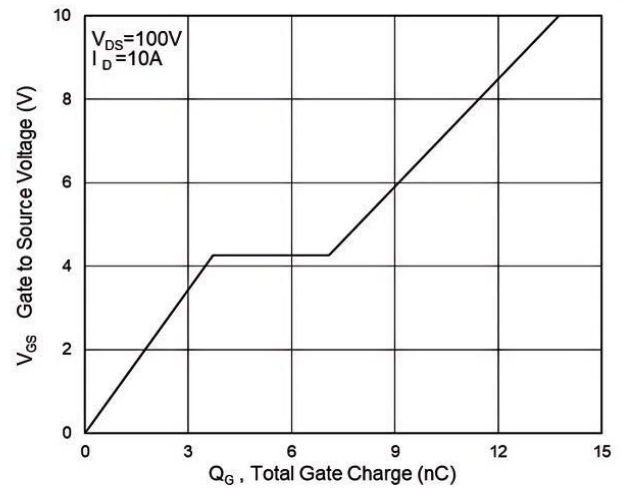
**Fig.1 Typical Output Characteristics**



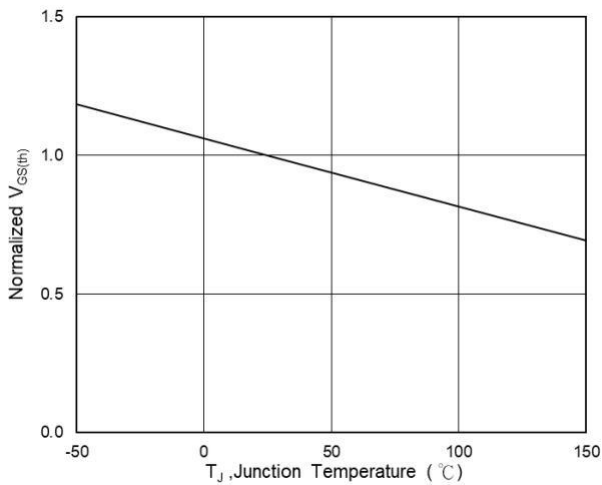
**Fig.2 On-Resistance vs. Gate-Source**



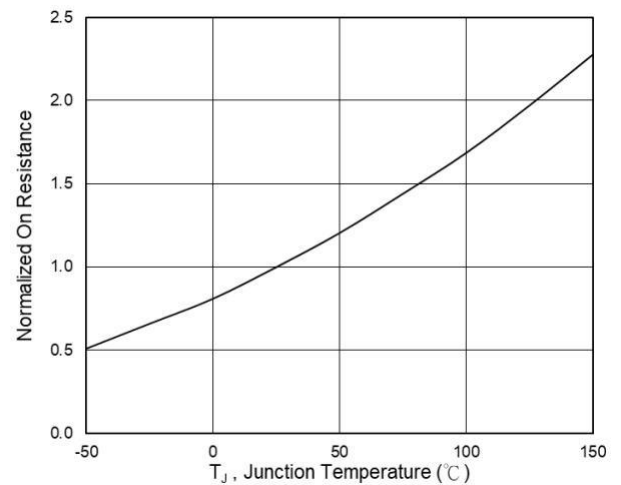
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**



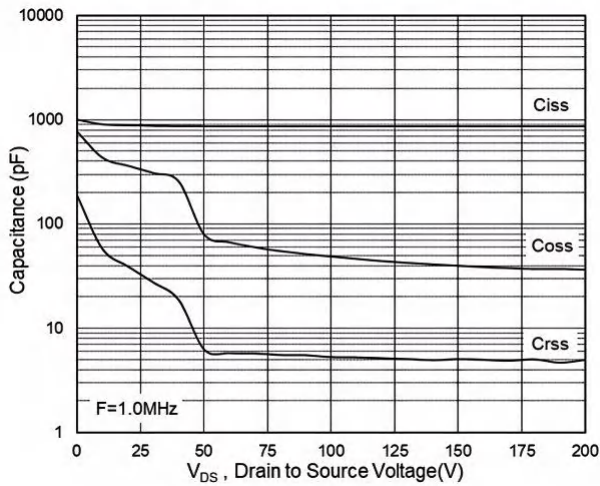
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



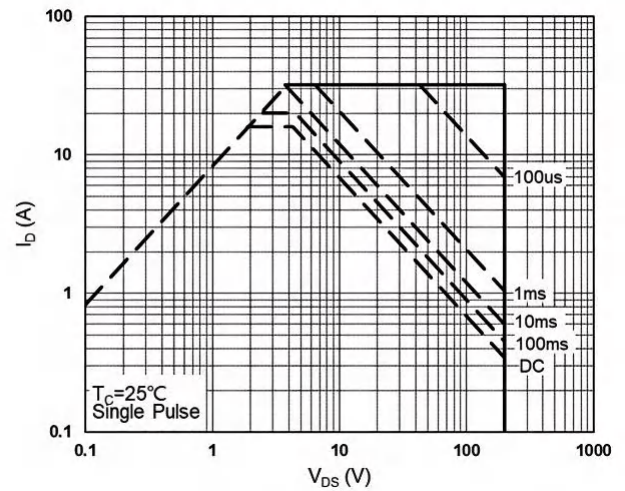
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



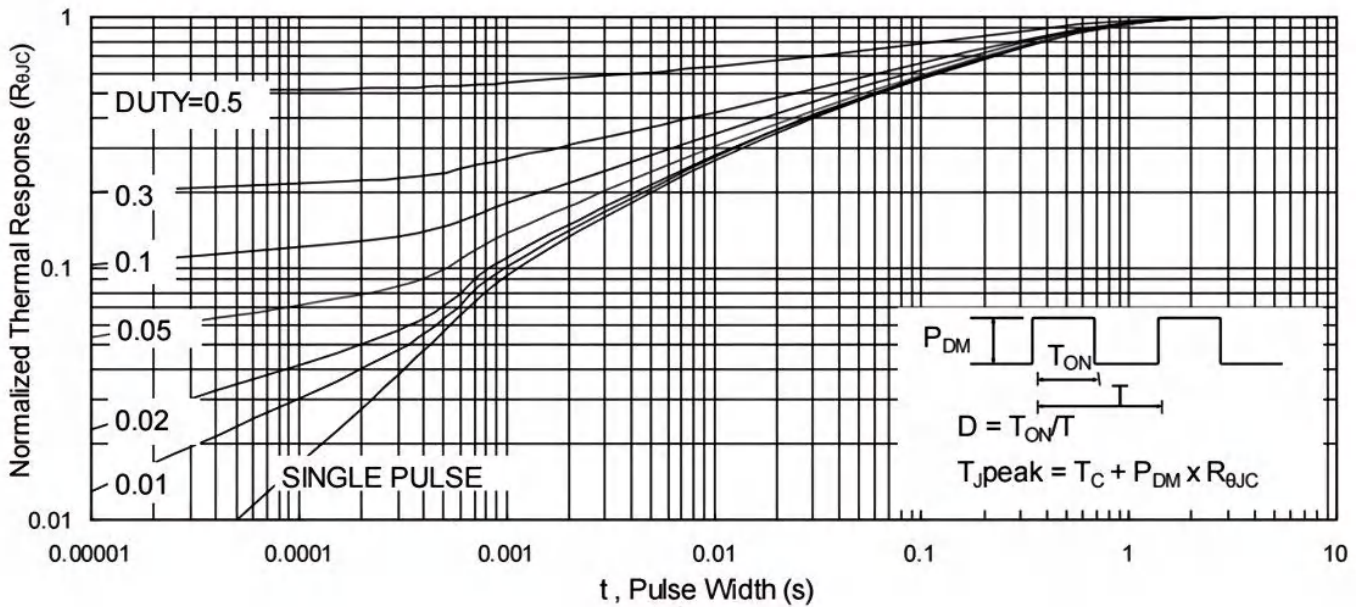
## N-Ch 200V Fast Switching MOSFETs



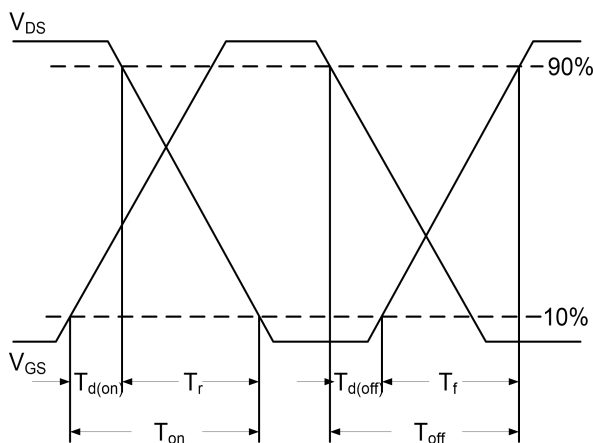
**Fig.7 Capacitance**



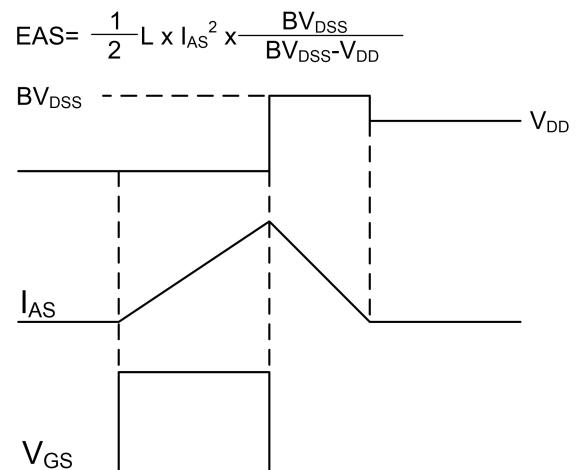
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**

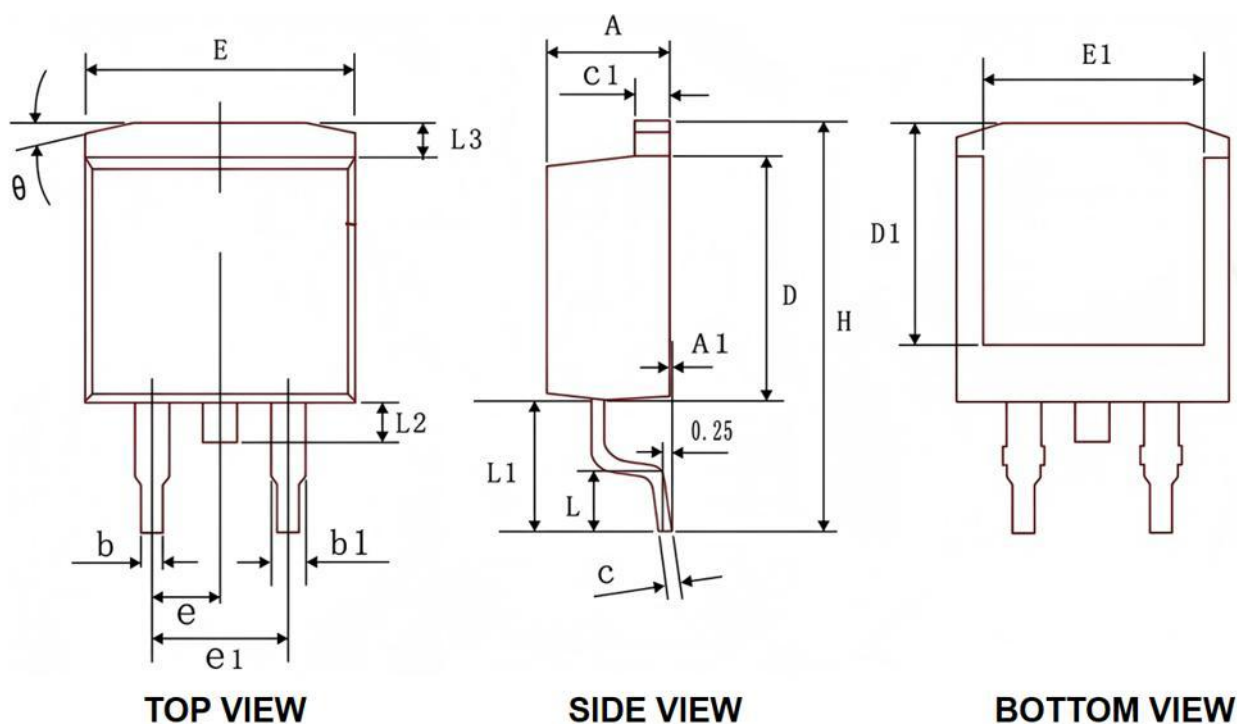


**Fig.11 Unclamped Inductive Switching Waveform**

## Ordering Information

| Part Number | Package code | Packaging     |
|-------------|--------------|---------------|
| HSH18N20A   | TO-263       | 800/Tape&Reel |

**TO-263 Package Outline**



**COMMON DIMENSIONS(UNIT OF MEASURE - MM)**

| SYMBOL   | MIN      | NOM   | MAX  |
|----------|----------|-------|------|
| A        | 4.37     | 4.57  | 4.77 |
| A1       | 0.00     | -     | 0.25 |
| b        | 0.70     | 0.83  | 0.96 |
| b1       | 1.00     | 1.24  | 1.47 |
| C        | 0.35     | 0.45  | 0.55 |
| C1       | 1.25     | 1.30  | 1.35 |
| D        | 8.50     | 8.90  | 9.30 |
| D1       | 7.50     | 8.00  | 8.50 |
| H        | 14.7     | 15.20 | 15.7 |
| E        | 9.80     | 10.08 | 10.4 |
| E1       | 7.35     | 7.80  | 8.25 |
| e1       | 4.93     | 5.08  | 5.23 |
| L        | 2.00     | 2.30  | 2.60 |
| L1       | 4.50     | 4.75  | 5.00 |
| L2       | 1.30     | 1.53  | 1.75 |
| L3       | 1.10     | 1.29  | 1.47 |
| e        | 2.54 BSC |       |      |
| $\theta$ | 13°TYP   |       |      |



## HSH18N20A Marking:

